

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): R. Shane Fazzio
Assignee: Avago Technologies, Ltd.
Title: Microcap Wafer Bonding Apparatus
Serial No.: 10/807,417 Filing Date: March 23, 2004
Examiner: Monica Lewis Group Art Unit: 2822
Docket No.: 10030899-1

San Jose, California
March 12, 2007

Mail Stop Amendment
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

This is a response to the December 12, 2006 Office Action, which has a statutorily shortened period for response that ends on March 12, 2007. Please amend the above-identified application as follows:

Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.